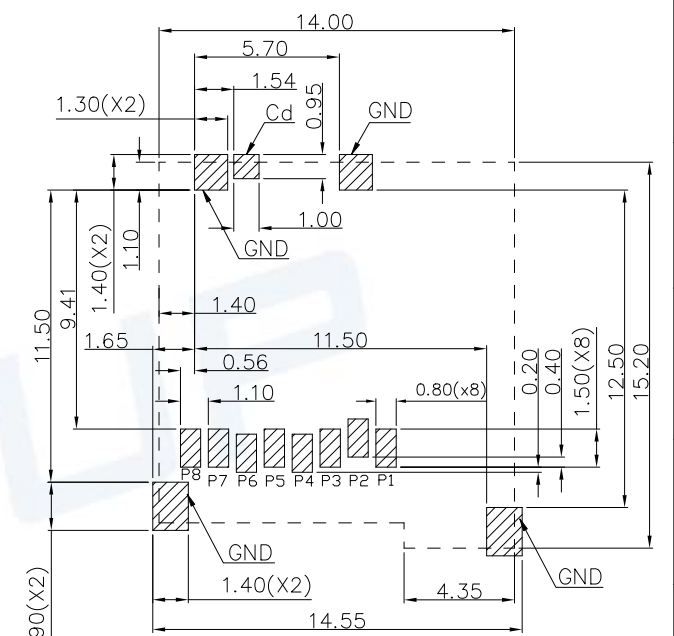
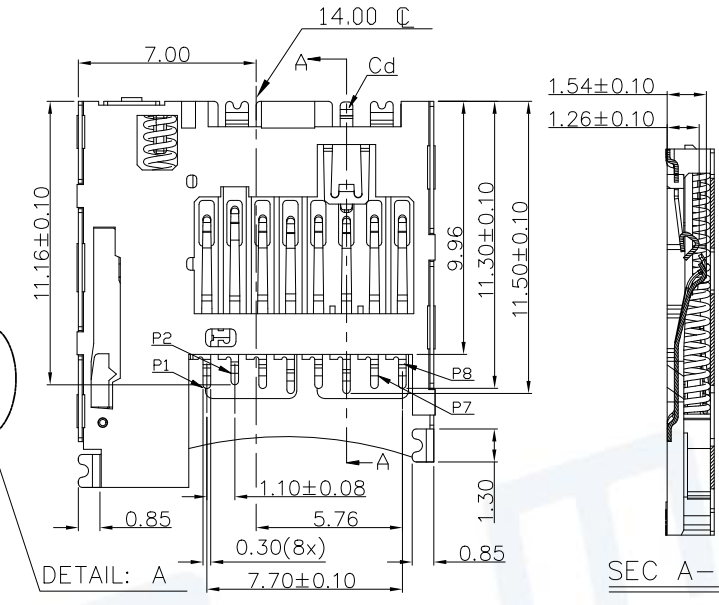
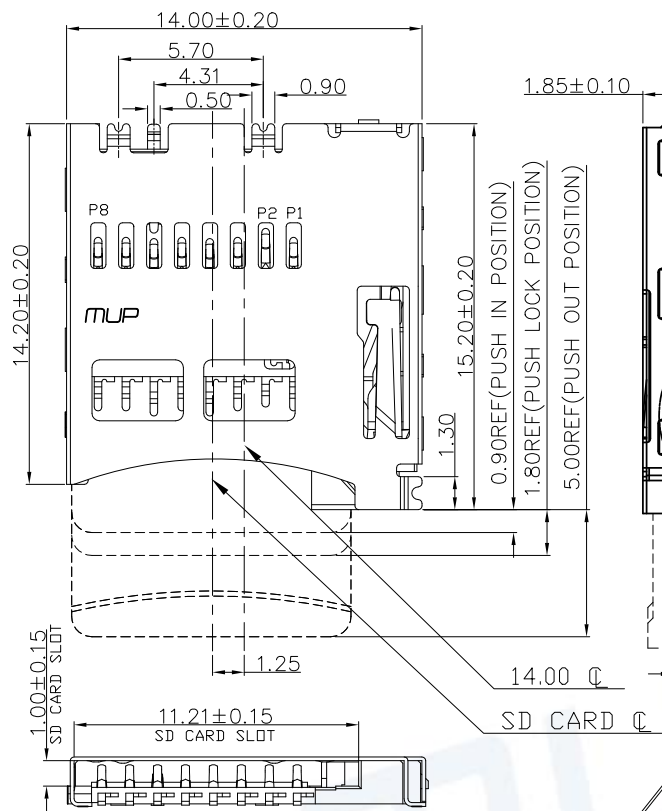
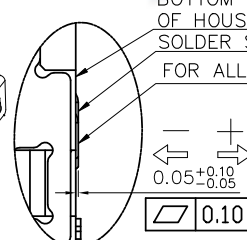


REV.	DESCRIPTION OF REVISIONS	APPR.	CHKD.	DRAW.	DATE
△	NEW			Henry	2018/05/18
△	Original Model M615-1			Henry	2023/10/24

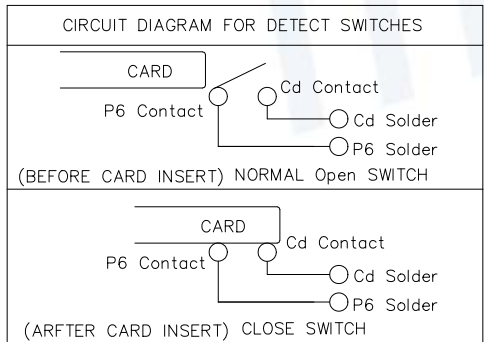


SEC A-A

BOTTOM SURFACE OF HOUSING
SOLDER SURFACE
FOR ALL SOLDER TAILS



DETAIL A
SCALE 2:1



TECHNICAL CHARACTERISTICS
 1.General Characteristics
 Dimensions: 15.20LX14.0WX1.90H mm
 Weight: Approx 0.5g
 Durability: 5,000 cycles min.
 2.Electrical Characteristics
 Contact resistance: 50mΩ typical,100mΩ max
 Insulation resistance: >1000MΩ/500V DC
 3.Solderability
 Vapor phase: 215°C,30sec.Max
 IR reflow: 260°C,10sec.Max
 Manual soldering: 370°C,3sec.Max
 4.Environmental Characteristics
 Operating temperature: -40°C~+85°C
 Operating humidity: 10%~+95%RH

Pin No.	Pin assigenment	Pin No.	Pin assigenment
1	DAT2	5	CLK
2	CD/DAT3	6	VSS
3	CMD	7	DAT0
4	VDD	8	DAT1
Cd	CARD DETECION	GND	GROUND

No.	DESCRIPTION	Q'TY	MATERIAL	FINISH
7	CD PIN	1	Copper Alloy	Contact area:Gold plated
6	CAM PIN	1	Stainless Steel	NO plating
5	HEART CAM	1	Hi-temp Thermoplastic	Black UL94V-0
4	SPRING	1	SWP.	Ni plating
3	SHELL	1	Stainless Steel	SMT area:Gold plated
2	TEMINAL	8	Copper Alloy	Contact area:Gold plated
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0

Unless otherwise specified, other tolerance are:

X	±0.35	X'	±5*
X.X	±0.25	X.X'	±4*
X.XX	±0.15	X.XX'	±3*
X.XXX	±0.10	X.XXX'	±2*

MUP MUP INDUSTRIAL CO.,LTD.

NAME: **MicroSD CARD CONNECTOR**
 MODEL NO: **MUP-M6015-01**
 TYPE: **With CD PIN**

PROJ. UNIT SCALE
 mm 1:1

DRAWN Henry May.18.2018 DWG NO.:
 CHECKED Henry May.18.2018 DWG-M6015-01-01
 APPROVAL Simon May.18.2018 SHEET 1/1 REVISION 2

